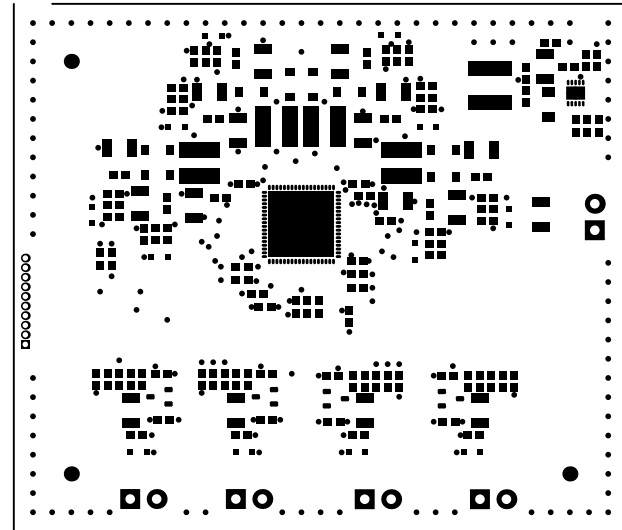
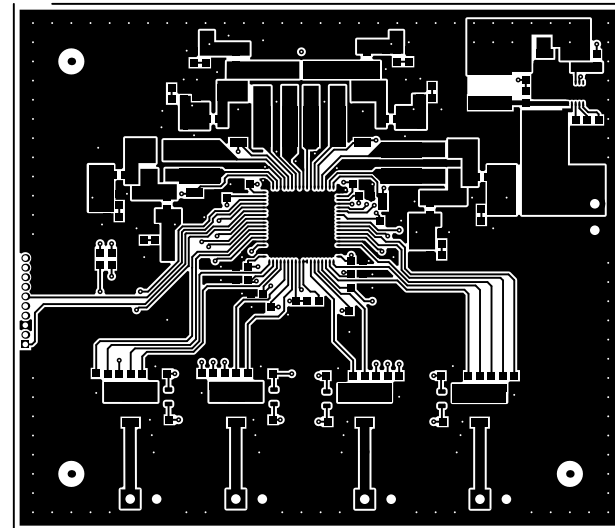


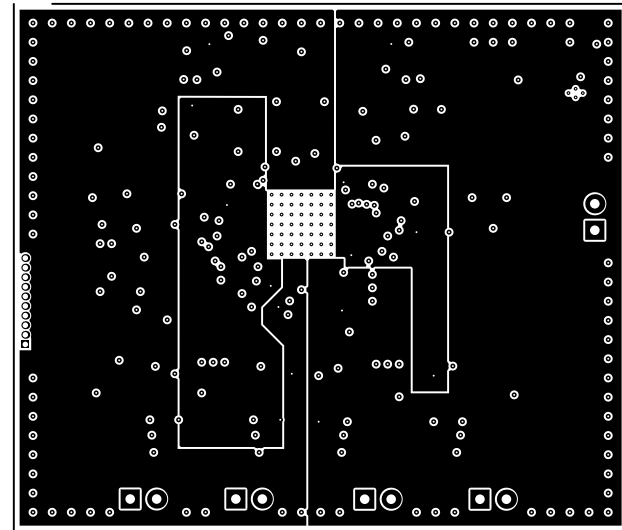
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Top Overlay	GENERATED : 2/8/2017 2:34:19 PM	TEXAS INSTRUMENTS	



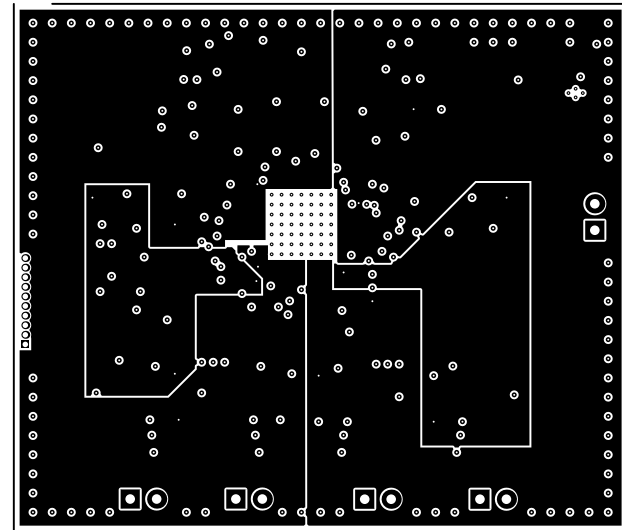
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Top Solder Mask	GENERATED : 2/8/2017 2:34:21 PM	TEXAS INSTRUMENTS	



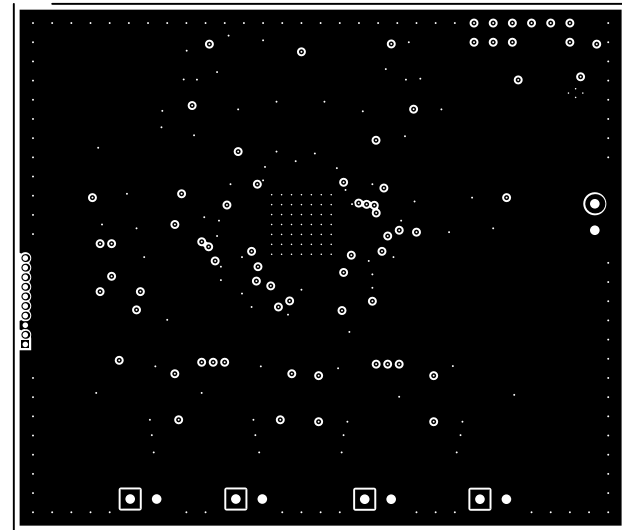
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Top Layer	GENERATED : 2/8/2017 2:34:22 PM	TEXAS INSTRUMENTS	



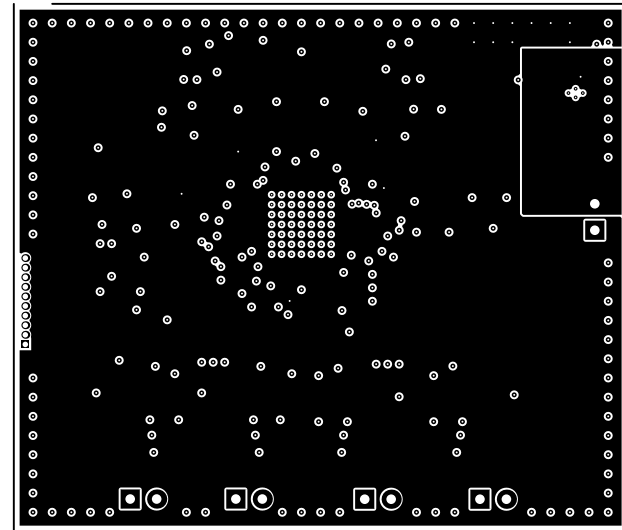
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Signal Layer 1	GENERATED : 2/8/2017 2:34:23 PM	TEXAS INSTRUMENTS	



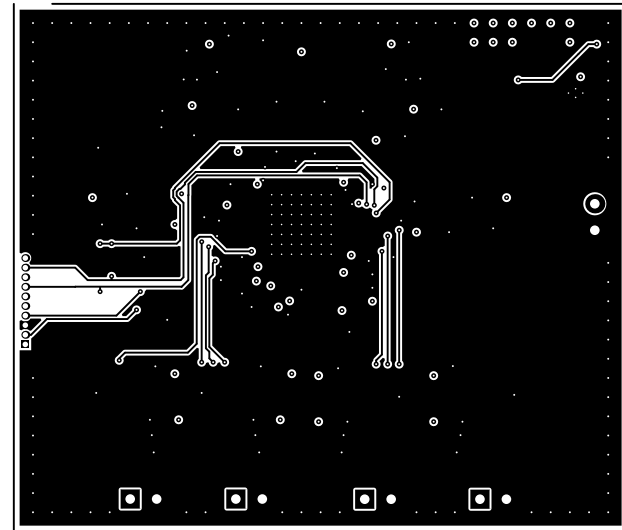
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Signal Layer 2	GENERATED : 2/8/2017	2:34:24 PM	TEXAS INSTRUMENTS



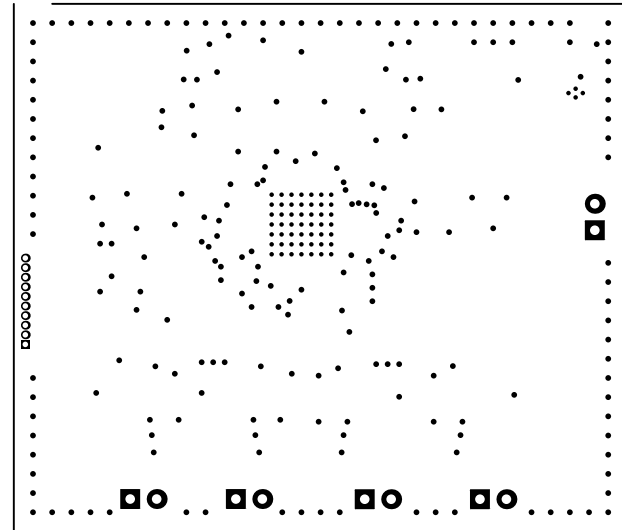
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Signal Layer 3	GENERATED : 2/8/2017 2:34:25 PM	TEXAS INSTRUMENTS	



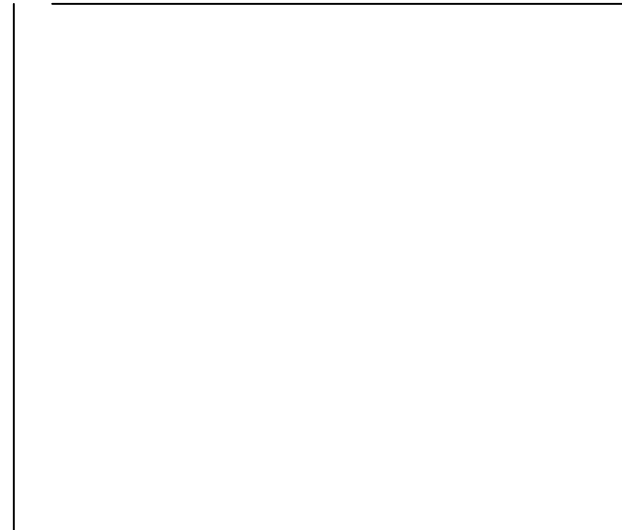
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Signal Layer 4	GENERATED : 2/8/2017	2:34:26 PM	TEXAS INSTRUMENTS



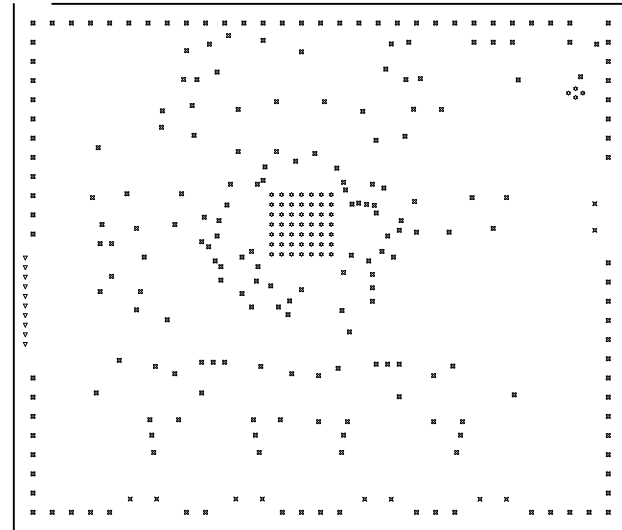
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Bottom Layer	GENERATED : 2/8/2017	2:34:27 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/8/2017	2:34:28 PM	TEXAS INSTRUMENTS

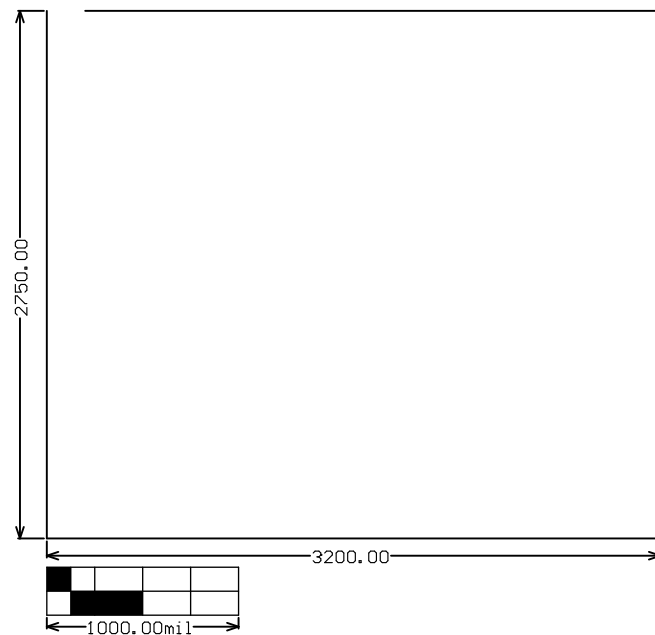


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Bottom Overlay	GENERATED : 2/8/2017 2:34:29 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊛	53	7.87mil (0.200mm)	PTH	Round
⊞	226	10.00mil (0.254mm)	PTH	Round
▽	10	28.74mil (0.730mm)	PTH	Round
⊞	10	50.00mil (1.270mm)	PTH	Round
	299 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Drill Drawing	GENERATED : 2/8/2017	2:34:30 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIPD215	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIPD215		
PLOT NAME = Board Dimensions	GENERATED : 2/8/2017	2:34:32 PM	TEXAS INSTRUMENTS

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